

Amendments to the Claims:

This listing of Claims replaces all prior versions and listings of Claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): A method of plating a substrate material, which when activated by laser light adsorbs seeding particles for an electroless plating process, comprising

- a) applying a strippable coating to a substrate surface to be plated, wherein the substrate is an aromatic polymer and the strippable coating is a non-aromatic polymer;
- b) selectively illuminating the coated substrate surface with laser light to ablate a selected area of the strippable coating and to activate an underlying region of the substrate surface exposed by the ablation of the strippable coating;
- c) contacting the activated region of the substrate surface with seeding particles for electroless plating, ~~so that~~ whereby the seeding particles adhere preferentially to the activated region of the substrate surface; and
- d) electrolessly plating the activated region of the substrate surface, whereby the seeded ~~areas~~ area of the substrate surface ~~are~~ is selectively plated.

Claim 2 (Original): A method according to claim 1, comprising removing the strippable coating after contacting the substrate surface with seeding particles but prior to electrolessly plating the substrate surface.

Claim 3 (Original): A method according to claim 1, comprising removing the strippable coating after electrolessly plating the substrate surface.

Claim 4 (Canceled)

Claim 5 (Previously Presented): A method according to claim 1, comprising using the same laser to ablate the strippable coating and to activate

the substrate surface, and reducing the power of the laser for the activation of the substrate surface.

Claim 6 (Previously Presented): A method according to claim 1, comprising depositing further metal on the electrolessly plated region of the substrate.

Claim 7 (Original): A method according to claim 6, comprising depositing the further metal by electroless plating.

Claim 8 (Original): A method according to claim 6, comprising depositing the further metal by electroplating.

Claim 9 (Currently Amended): A method according to claim 1, comprising ablating the substrate material underlying the ablated area of the strippable coating to form a recess in the substrate material before activating the ~~polymer~~ substrate surface.

Claim 10. (Original): A method according to claim 9, comprising fabricating fine-line circuitry by ablating channels in the substrate material and filling the channels with metal after electroless plating of the activated surfaces of the channels to form circuitry embedded in the substrate material.

Claim 11 (Previously Presented): A method according to claim 1, comprising using the laser to ablate the strippable coating, selectively activate the substrate surface and drill a landless via in the substrate material in the same step.

Claim 12 (Original): A method according to claim 11, wherein the landless via is noncircular.

Claim 13 (Original): A method according to claim 12, wherein the non-circular landless via is slot-shaped.

Claim 14 (Currently Amended): A method according to claim 1, comprising ~~selectively electrolessly~~ plating non-planar features on the substrate surface.

Claim 15 (Currently Amended): A method according to claim 1, comprising ~~forming an integrated resistor by~~ selectively activating and plating a region, adsorbing seeding particles on the region and electrolessly plating the region on the substrate surface between two circuit interconnects placed on the substrate surface and thereby forming an integrated resistor.

Claim 16 (Original): A method according to claim 15, comprising plating the activated region with a nickel alloy to form the resistor.

Claim 17 (Currently Amended): A method ~~according to claim 1 used to~~ for re-mapping a wafer[[.]] comprising

- a) applying an aromatic polymer layer to the wafer to be re-mapped;
- b) covering the aromatic polymer layer with a strippable coating, which is a non-aromatic polymer;
- c) selectively illuminating the coated aromatic polymer layer surface with laser light to ablate a selected area of the strippable coating and to activate an underlying region of the aromatic polymer layer surface exposed by the ablation of the strippable coating;
- d) contacting the activated region of the aromatic polymer layer surface with seeding particles for electroless plating; and
- e) electrolessly plating the activated region of the aromatic polymer surface, whereby the seeded area of the aromatic polymer substrate surface is selectively plated.

Claims 18-20 (Canceled)

Claim 21 (New): A method according to claim 17 comprising ablating through the strippable coating; drilling vias and activating the exposed surface of the aromatic polymer layer.

Claim 22 (New): A method according to claim 17 wherein the strippable coating is removed after the activated surface is seeded and prior to the seeded surface is plated.

Claim 23 (New): A method according to claim 1 wherein the aromatic polymer is polyimide, polycarbonate or an epoxy polymer.

Claim 24 (New): A method according to claim 1 wherein the substrate is immersed in a seeding solution for electroless plating, containing polymer-stabilised catalytic particles such as polyvinylpyrrolidone stabilised palladium particles.

Claim 25 (New): A method according to claim 15 wherein the two interconnects placed on the substrate are copper interconnects.